

SPECIFICATION SHEET

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SPECIFICATION SHEET NO.	R0813- YR32K76800S105		
DATE	Aug. 13, 2	2024	
REVISION	A1	Updated With Most Recent Data	
DESCRIPTION AND		Crystals, L3.2*W1.5*H0.9mm, 2 Pads, YR series KHz, Tolerance: ±10ppm, CL 9pF	
MAIN PARAMETRICS	Operating	Temp. Range -40°C ~+85°C, ESR 70 Kohm Max.,	
	Reflow Pr	ofile Condition 260 °C Max.	
	Tape/Reel, 3000pcs/Reel, RoHS/RoHS III compliant		
CUSTOMER			
CUSTOMER PART NO.			
CROSS REF. PART NO.			
ORIGINAL MFG/PART NO.	ECEC/MF3215-32.768K10-9-40-70		
PART CODE	YR32K76800S105		

VENDOR APPROVE

Issued/Checked/Approved







DATE: Aug. 13, 2024

CUSTOMER APPROVE		
DATE:		



KHZ SMD CRYSTALS 3215 TYPE YR SERIES

MAIN FEATURE

- SMD Package, L3.2*w1.5*h0.9mm, 2 Pads
- Industry Standard
- Reflow Profile Condition 260 °C Max.
- Cross More Competitors Part
- REACH/RoHS III Compliant





APPLICATION

• Small Communications Devices And More

HOW TO ORDER

• Please follow up Part Code Guide and Indicate Part Code When You Order Or RFQ.

PART CODE GUIDE



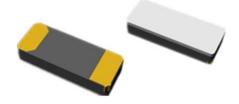
CODE	NAME	KEY SPECIFICATION OPTION
YR	Series Code	Part family Code for KHz SMD crystal L3.2*W1.5*H0.9mm, 2 Pads
32K768	Frequency Range Code	Frequency Range Code For 32.76800KHz
005	Internal Control Code	Special letter A~Z, a~z or digits (1-9)
105	Parameters code	Special Parameters Code letter A~Z, a~z or digits (1-9)

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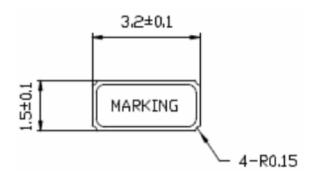
DIMENSION (Unit: mm)

Image for reference

Image shown is a representation only. Exact specifications should be obtained from the product dimension.



Top View



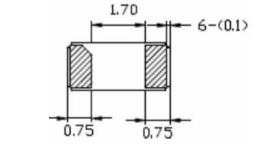
Marking

Frequency Range

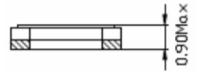
or

Marking Internal Control Code

Bottom View

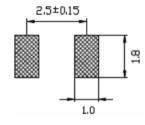


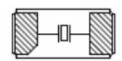
Side View



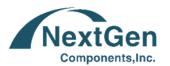


Land Pattern for reference





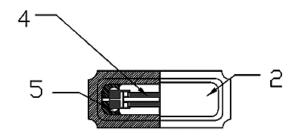
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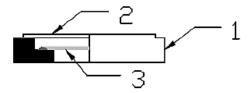


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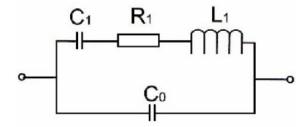
PRODUCT STRUCTURE

EQUIVALENT CIRCUIT





Item	Component	Material
No.	Name	Name
1	Crystal Case	Ceramic
		+Au Plating
2	Crystal	Fe ALLOY
	Cover/Lid	
3	Crystal SiO2	
	Chip/Blank	
4	Internal	Ag、Au
	Electrode	
5	Conductive	Ag + Slicon
	Adhesive	





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ELECTRICAL PARAMETERS – FOR DIFFERENT PART CODE- Ta = 25°C

Part Code	Frequency Range	Frequency Tolerance @ 25°C±3°C	Load Capacitance	
	KHz	ppm	pF	Code
YR32K76800S101	32.768	±10	12.5	E
YR32K76800S103	32.768	±10	7	j
YR32K76800S104	32.768	±10	6	w
YR32K76800S105	32.768	±10	9	С

GENERAL ELECTRICAL PARAMETERS

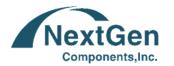
PARAMETER	UNITS	VALUE		CONDITION	
		MIN.	TYPICAL	MAX.	
Mode of Oscillation		,	AT Fundamen	tal	
Equivalent Series Resistance (ESR)	ΚΩ	-	-	70	
Parabolic Coefficient	ppm/°C²	-0.04	-	-0.02	
Drive Level (DL)	μW	-	0.1	0.5	
Shunt Capacitance (C0)	pF	-	-	2.0	
Dynamic Capacitance (C1)	fF	-	4.1	-	
Turnover Temperance	°C	+20	25	+30	
Insulation Resistance	ΜΩ	500			@100VDC ± 15VDC
Quality Factor (Q)	К	13	-	-	
Operation Temperance	°C	-40	-	+85	
Storage Temperance	°C	-55	-	+125	
Aging	ppm	-3	-	+3	Per Year



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RELIABILITY

TEST ITEMS	TEST METHOD AND CONDITIONS	TEST STANDARD
High Temperature High Humidity Storage	Temperature: 60°C ± 2 °C Relative Humidity: 90%~95% RH For Time: 500 ± 12 Hours	A, C, D, G
High Temperature Storage	Temperature: 125°C ± 2°C Time: 1000±12 Hours.	В, С, G
Low Temperature Storage	Temperature: $-40^{\circ}\text{C} \pm 2^{\circ}\text{C}$ Time: 500 ± 12 Hours.	A, C, G
Temperature Cycle	The crystal unit shall be subjected to 100 successive change of temperature cycles. $ +85+4/-0^{\circ}C $ $ +25\pm2^{\circ}C $ $ -40+0/-6^{\circ}C $ $ 30\pm3min $ $ 3min. max. $ $ 1 Cycle $	A, C, G
Solderability	The solder pot temperature is 260±5°C , dwell time 2±0.6sec	F
Drop Test	Height: 180 cm; Dropped Cycle: 3 cycles; Drop it on to a concrete board for 6 Directions (X,Y,Z), that should be 1 cycle	В, С
Vibration	Frequency Range: 10Hz ~ 55Hz Amplitude: 1.5mm±15%; Sweep time: 2~3 Minutes, 2 Hours in each direction, total 6 Hours	A, C
Leakage Test	Helium Bombing 5.0 ~5.5 Kgf/cm²; for 2 hours	E



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RELIABILITY

TEST ITEMS	TEST METHOD AND CONDITIONS	TEST STANDARD
Terminal Strength	Shall be pressurized at a speed of approx. 0.5mm/sec. in the direction indicated by the arrow unit the bending width reaches 3mm and held for 5 sec. PRESSURE ROD R20 R5 SAMPLE R5 45±2 45±2 R5	B, C
Sticking Tendency	A R0.5 Jig shall be used to apply a 10N dead load in the direction indicated by the arrow to the element and retain it for 10 sec. JIG R0.5 SAMPLE	В, С
Element Assembly Strength	A R0.5 Jig shall be used to apply a 10N dead load in the direction indicated by the arrow to the element and retain it for 10 sec.	B, C

NextGen Components, Inc.



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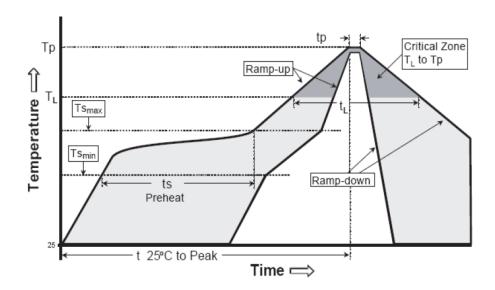
TEST STANDARD

TEST STANDARD SYMBOL	SPECIFICATION	VALUE
А	Frequency Change permitted	ΔF≤10ppm
В	Frequency Change permitted	ΔF≤20ppm
С	Equivalent Series Resistance Change Permitted	ΔCI≤5KΩ or 20%
D	Insulation Resistance	>500 MΩ
E	Leak Rate Less than	<1*1E-9 Pa·m³/sec.
F	A new uniform coating of solder shall cover a Min 95% of the crystal surface	
G	Then 25 ± 2°C over 2 hours before Testing	



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SUGGESTED REFLOW PROFILE (For Reference No. JEDEC J-STD-020D)

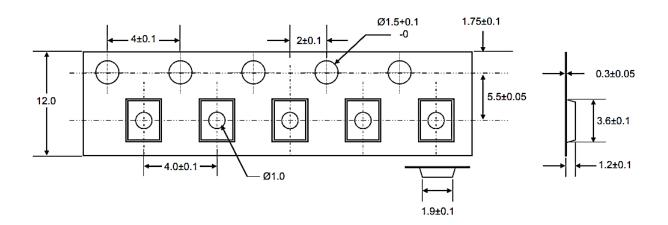


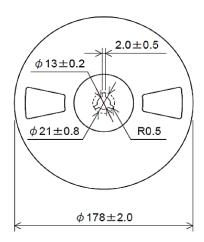
PROFILE FEATURE		PB-FREE ASSEMBLY
Average Ramp-up Rate (Ts Max to Tp)		3°C/second Max
Preheat Temperature Min (Ts Min.)		150°C
	Temperature Max (Ts Max.)	200°C
	Time (ts Min. to ts Max.)	60 ~ 120 seconds
Time maintained above	Temperature (TL)	217°C
	Time (tL)	60 ~ 150 seconds
Peak/Classification Temperature (Tp)		260 +/-5°C
Time within 5°C of actual Peak Temperature (tp)		20 ~ 40 seconds
Ramp-down rate		6 °C /Second Max.
Time 25 °C to Peak Temperature		8 minutes Max.
Suggest reflow times		3 Times Max.

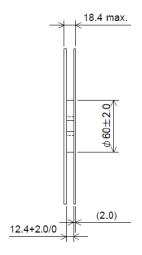
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REEL AND TAPE DIMENSION (Unit: mm)

All Devices are packed in accordance with EIA standard RS-481-2 and specifications, 3000pcs/Reel







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NOTES BEFORE USE

Ultrasonic Cleaning:

General cleaning solutions or ultrasonic cleaning method may be used to clean our products. However, under certain circumstances, ultrasonic cleaning machine could generate resonance at the oscillation frequency of our products and thus deteriorate the electrical characteristics in device and even damage the overall structure of device. Therefore, verification test is recommended before cleaning.

Ultrasonic Welding

Avoid mounting and processing by Ultrasonic welding this method has a possibility of an excessive vibration spreading inside the crystal products and become the cause of characteristic deterioration and not oscillating.

Storage Temperature Description

Storage Temperature is only for the product itself, the temperature for the packing material is 5~40°C Recommended Conditions for Manual Welding Max. Temperature: 350±10°C, Time: 3 sec Max., Re-solder time: twice Max.

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IMPORTANT NOTES AND DISCLAIMER

- ROHS COMPLIANCE: The levels of RoHS restricted materials in this product are below the maximum
 concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an
 exempted application, in accordance with EU RoHS Directive (EU) 2015/863 EC (RoHS3). RoHS Test Report for
 this product can be obtained can be obtained at Download Center.
- REACH COMPLIANCE: REACH substances of high concern (SVHCs) information is available for this product.
 Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, REACH Test Report for this product can be obtained can be obtained at Download Center.
- All Product parametric performance is indicated in the Electrical Characteristics for the listed herein test
 conditions, unless otherwise noted. Product performance may not be indicated by the Electrical
 Characteristics if operated under different conditions.
- 4. NextGen Component, Inc (*NextGen*) reserves the right to make changes to this document and its products and specifications at any time without notice. Customers should obtain and confirm the latest product information and specifications before final design, purchase or use.
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 express written approval by NextGen.
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Non-Cancelable/ Non-Returnable (NCNR). These products are not returnable and not refundable.